

Abstract of the Disclosure:

A filter device and a method for fabricating filter devices can package filters, especially acoustic wave filters, by bonding a carrier (substrate) wafer carrying manufactured filters to another wafer referred to as a capping wafer. A capping wafer/substrate eliminates the need for a conventional package to protect the sensitive filters, which reduces both product size and product costs significantly. Even though additional packaging is possible (i.e. in plastic molded packages, or in glob-top packages), it is not required for the reliability of the filters.

15

20

LAG/nt